

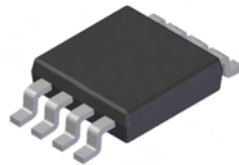
Features

- Low On-Resistance
 - 7mΩ @ $V_{GS} = 10V$
 - 10mΩ @ $V_{GS} = 4.5V$
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- **Lead Free By Design/RoHS Compliant (Note 2)**
- **"Green" Device (Note 4)**
- **Qualified to AEC-Q101 Standards for High Reliability**

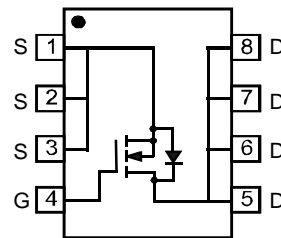
Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram
- Terminals: Finish - Matte Tin annealed over Copper lead frame. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 4
- Ordering Information: See Page 4
- Weight: 0.072g (approximate)

SO-8



Top View


 Top View
Internal Schematic

Maximum Ratings @ $T_A = 25^\circ C$ unless otherwise specified

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V_{DSS}	30	V
Gate-Source Voltage			V_{GSS}	± 20	V
Drain Current (Note 1)	Steady State	$T_A = 25^\circ C$	I_D	16	A
		$T_A = 70^\circ C$		13	
Pulsed Drain Current (Note 3)			I_{DM}	64	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 1)	P_D	2.5	W
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	50	$^\circ C/W$
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ C$

- Notes:
1. Device mounted on 2 oz. Copper pads on FR-4 PCB, with $R_{\theta JA} = 50^\circ C$
 2. No purposefully added lead.
 3. Pulse width $\leq 10\mu S$, Duty Cycle $\leq 1\%$.
 4. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 5)						
Drain-Source Breakdown Voltage	BV _{DSS}	30	—	—	V	V _{GS} = 0V, I _D = 250μA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	1	μA	V _{DS} = 30V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS (Note 5)						
Gate Threshold Voltage	V _{GS(th)}	1.3	—	2.1	V	V _{DS} = V _{GS} , I _D = 250μA
Static Drain-Source On-Resistance	R _{DS(on)}	—	5 7.9	7 10	mΩ	V _{GS} = 10V, I _D = 15A V _{GS} = 4.5V, I _D = 13A
Forward Transconductance	g _{fs}	—	16.4	—	S	V _{DS} = 10V, I _D = 15A
Diode Forward Voltage (Note 5)	V _{SD}	—	0.67	1.2	V	V _{GS} = 0V, I _S = 2.3A
DYNAMIC CHARACTERISTICS						
Input Capacitance	C _{iss}	—	2714	—	pF	V _{DS} = 15V, V _{GS} = 0V f = 1.0MHz
Output Capacitance	C _{oss}	—	436	—	pF	
Reverse Transfer Capacitance	C _{rss}	—	380	—	pF	
Gate Resistance	R _G	—	0.7	—	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1.0MHz
SWITCHING CHARACTERISTICS						
Total Gate Charge	Q _g	—	31.2 64.2	—	nC	V _{DS} = 15V, V _{GS} = 4.5V, I _D = 16A V _{DS} = 15V, V _{GS} = 10V, I _D = 16A
Gate-Source Charge	Q _{gs}	—	7.1	—		V _{DS} = 15V, V _{GS} = 10V, I _D = 16A
Gate-Drain Charge	Q _{gd}	—	17.1	—		V _{DS} = 15V, V _{GS} = 10V, I _D = 16A
Turn-On Delay Time	t _{d(on)}	—	10.3	—	ns	V _{DS} = 15V, V _{GS} = 10V, I _D = 1A, R _G = 6.0Ω
Rise Time	t _r	—	14.8	—		
Turn-Off Delay Time	t _{d(off)}	—	85.1	—		
Fall Time	t _f	—	43.6	—		

Notes: 5. Short duration pulse test used to minimize self-heating effect.

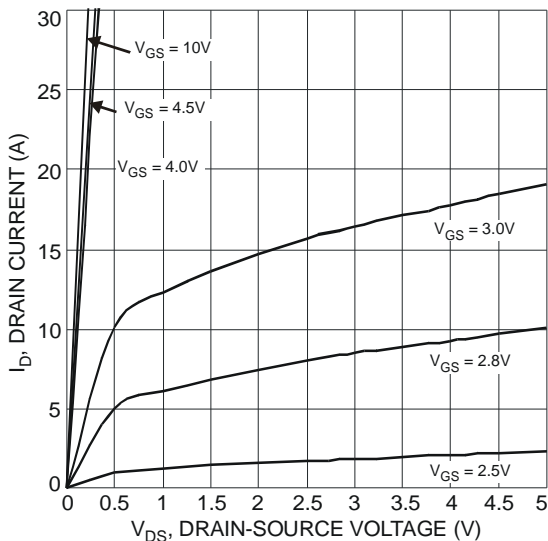


Fig. 1 Typical Output Characteristic

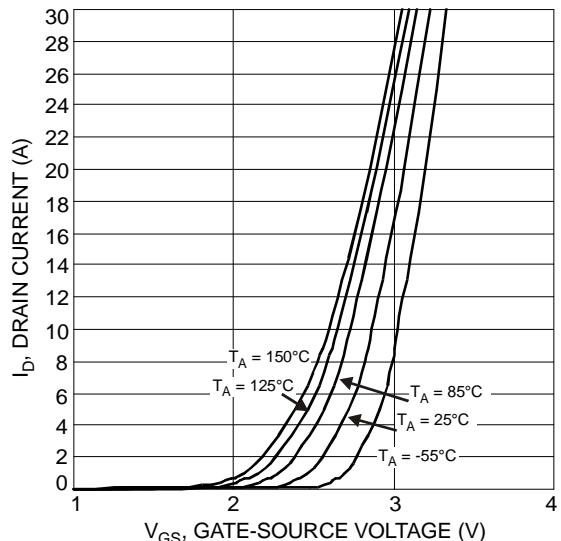


Fig. 2 Typical Transfer Characteristic

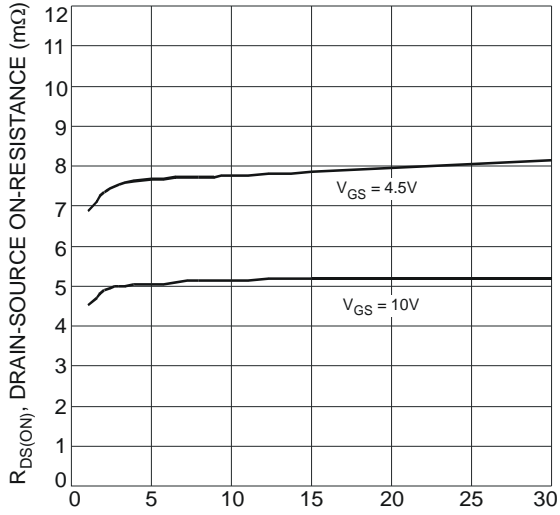


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

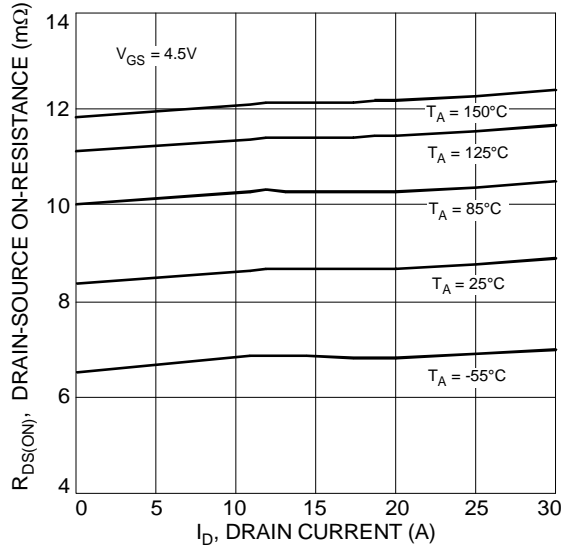


Fig. 4 Typical On-Resistance vs. Drain Current and Temperature

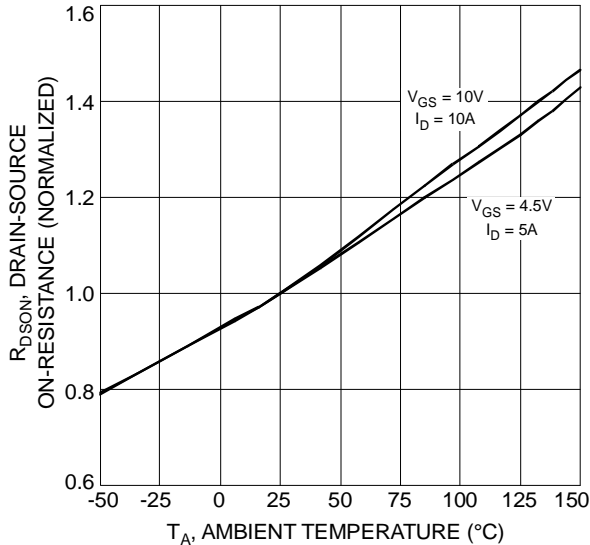


Fig. 5 On-Resistance Variation with Temperature

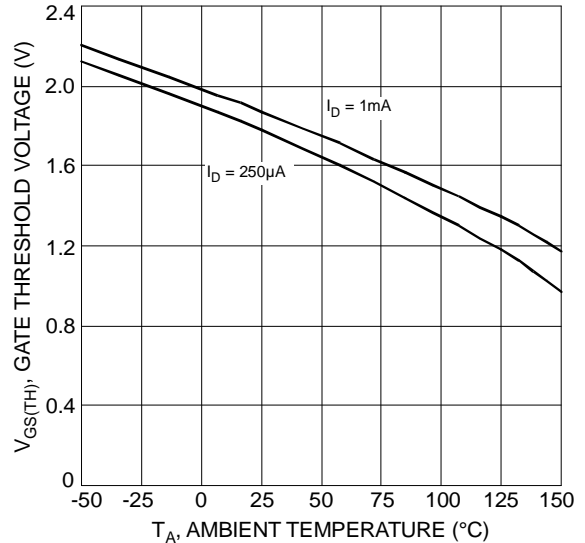


Fig. 6 Gate Threshold Variation vs. Ambient Temperature

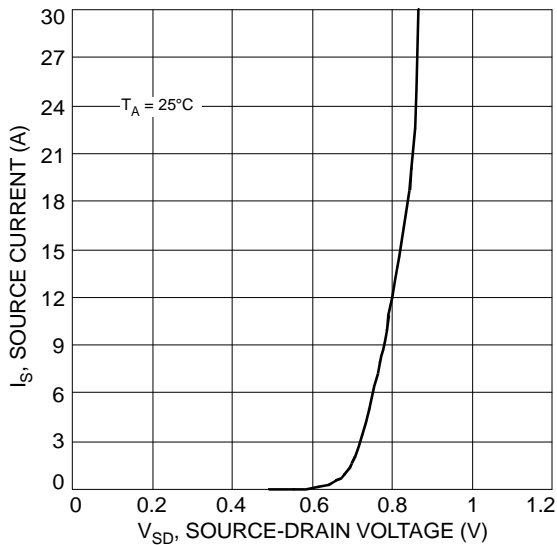


Fig. 7 Diode Forward Voltage vs. Current

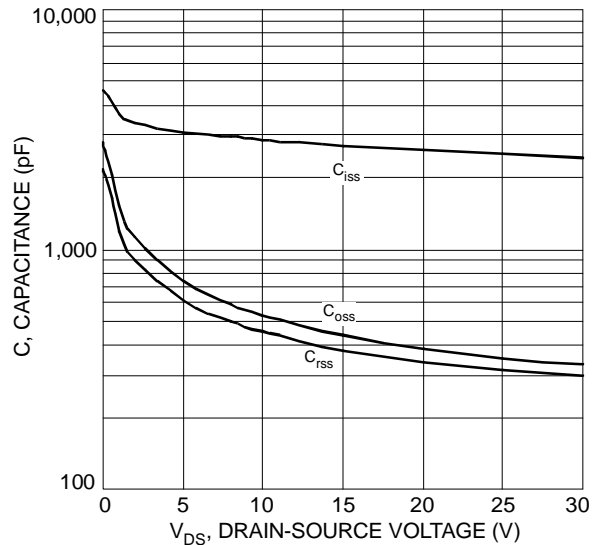


Fig. 8 Typical Total Capacitance

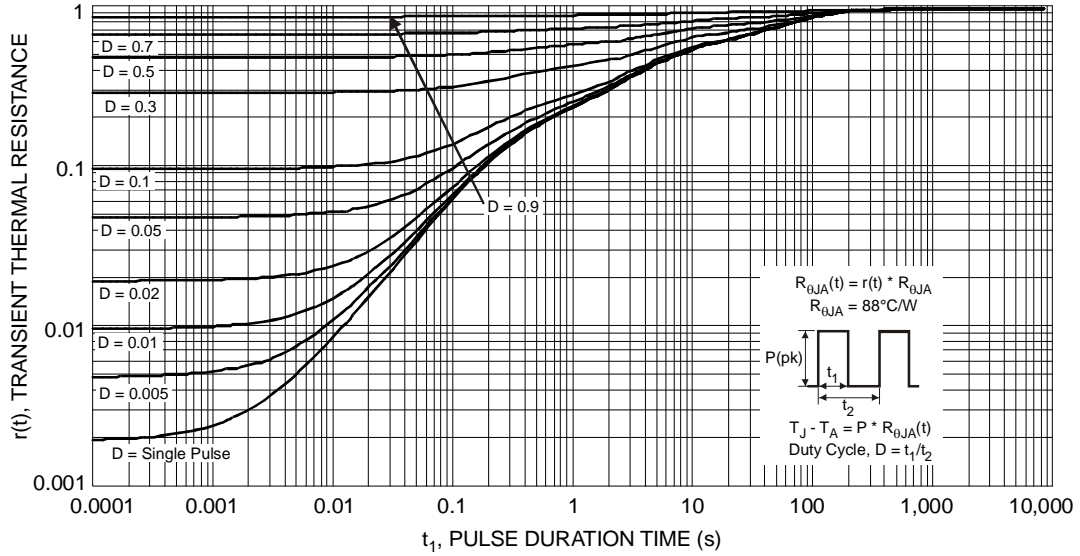


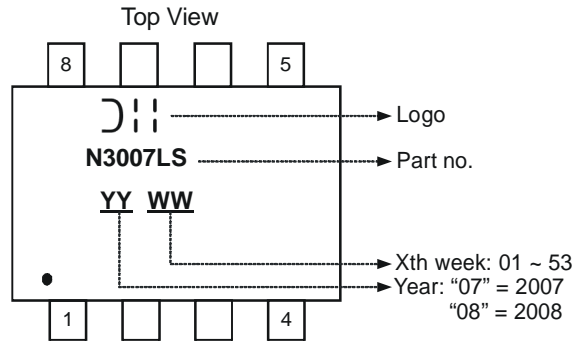
Fig. 9 Transient Thermal Response

Ordering Information (Note 6)

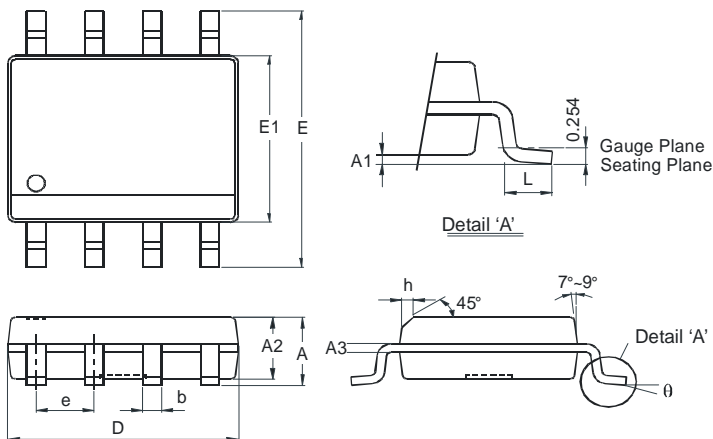
Part Number	Case	Packaging
DMN3007LSS-13	SO-8	2500/Tape & Reel

Notes: 6. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information

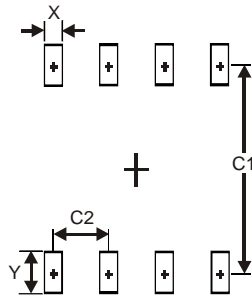


Package Outline Dimensions



SO-8		
Dim	Min	Max
A	-	1.75
A1	0.10	0.20
A2	1.30	1.50
A3	0.15	0.25
b	0.3	0.5
D	4.85	4.95
E	5.90	6.10
E1	3.85	3.95
e	1.27 Typ	
h	-	0.35
L	0.62	0.82
θ	0°	8°
All Dimensions in mm		

Suggested Pad Layout



Dimensions	Value (in mm)
X	0.60
Y	1.55
C1	5.4
C2	1.27

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